

SPAR - BRAMPTON (SSS)

9445 AIRPORT RD

### Critical Items List

SRMS

BRAMPTON ONTARIO L6S4J3

CIL Ref#: 2631

Revision: 0

FMEA Rev: 0

System: SRMS

Subsystem: ELECTRICAL SUB-SYSTEM

Assembly Desc: Servo Power Amplifier

Part Number(s): 51140F1177-3

51140F1177-5

Item:

Function: Central Processing Unit Assembly

Analog Interface Assembly

Provides hardware and software necessary to implement servo control loops, control operation of the Analog I/F, Digital I/F and MDA boards and communicate with the MCIU. Provides PLL and frame sync BITE as well as a hardware watchdog timer to monitor health of microcomputer itself.

Provides Tachometer excitation, SCU signal filtering, Phase Locked Loop and tachometer counter circuits to provide measured motor speed data to inner and outer rate loops. Provides analog to digital conversion of MDA buck output voltage, EPC +5V and reference voltages for BITE.

Failure Mode: Loss of or Erroneous Digital Tach output.

H/W Func. Screen Failures

Criticality: 2 1R

Mission Phase: Orbit

Cause(s): Analog Interface Assembly

Amplification of unwanted 25 KHz content in SCU output.

Erroneous prime inner or outer tachometer data.

Erroneous redundant inner or outer tach data.

Loss of inductosyn sensor excitation SINE or COSINE channel.

Loss of PLL phase detector pump down operation.

Loss of PLL phase detector pump up operation.

Loss of prime and redundant outer digital tach.

PLL loses lock, tach data does not cause a s/w exception.

PLL loses lock.

Induced loss of PLL lock.

Loss of outer rate loop timer.

Loss of prime and redundant outer digital tach.

Central Processing Unit Assembly

Failure effect on unit/end item:

Inner and/or Outer and/or Prime and/or Redundant digital tachometer data is corrupt. TCO BITE will detect that prime/redundant tachometer data does not agree, Position Encoder BITE will detect that tachometer data is inconsistent with position encoder data, or PLL BITE will detect failures of the PLL circuit which corrupt the tach data.

Worst Case: Unexpected motion Joint runaway Autobrake

The design utilizes proven circuit techniques and is implemented using CMOS logic devices. CMOS devices operate at low power and do not experience significant operating stresses. The technology is mature, and device reliability history is well documented. All stresses are additionally reduced by derating the appropriate parameters in accordance with SPAR-RMS-PA.003. Special handling precautions are used at all stages of manufacture to preclude damage/stress due to electrostatic discharge.

Field Programmable Gate Arrays (FPGA's) and the Error Detection and Correction (EDAC) are semi-custom microcircuits in which the basic design functional elements are designed by the manufacturer. The interconnection of these elements is then customized by Spar to provide the functionality of the completed microcircuit. The design utilizes proven circuit techniques and is implemented using CMOS technology. This technology operates at low power and hence the device does not experience significant operating stresses. The technology is mature, and the basic device reliability is well documented. All stresses are additionally reduced by derating the appropriate parameters in accordance with SPAR-RMS-PA.003 and verified by design review.

This approach has a significant advantage in that it reduces the quantity of discrete parts required in the assembly and also the complexity of the PWB and results in significant weight and volume savings. This type of semi-custom part has been successfully used in other space applications.

The parts are qualified to the requirements of the applicable specification. They are 100% screened and burned in to the requirements of this Spar requirements document.

Comparators and operational amplifiers are standard linear integrated circuits with mature manufacturing technology. Application constraints are in accordance with SPAR-RMS-PA.003.

The Intel 80186 microprocessor is used in this design. This device, designed for use in conjunction with its corresponding high reliability support devices (EPROM, SRAM) comprises a processor kernel proven in many high reliability applications.

Resistors and capacitors used in the design are selected from established reliability (ER) types. Life expectancy is increased by ensuring that all allowable stress levels are derated in accordance with SPAR-RMS-PA.003. All ceramic and electrolytic capacitors are routinely subjected to radiographic inspection in accordance with the requirements of MSFC-STD-355.

The SPA board is fabricated using Surface Mount Technology (SMT). This is a PWB assembly technology in which the components are soldered to the solder pads on the surface of the PWB. The significant advantage of this technology is to enable the parts on the board to be more densely packed, to reduce the overall volume and weight of the assembly.

The assembly process is highly automated. The parts are mounted on the boards using a computer controlled "pick and place" machine. The subsequent soldering operation is performed using a belt furnace, in which the time and temperature thermal profile that the PWB assembly is exposed to is tightly controlled and optimized to ensure proper part soldering attachment. The assembly is manufactured under documented procedures and quality controls. These controls are exercised throughout the assembly, inspection and testing of the unit. This inspection includes workmanship, component mounting, soldering, and conformal coating to ensure that it is in accordance with the NHB 5300 standards.

The SMT line used for the SPA PWB assembly has undergone a full qualification program, and assemblies produced on this line are used in other space programs.

The circuit board design has been reviewed to ensure adequate conductor width and separation and to confirm appropriate dimensions of solder pads and of component hold provisions. Parts mounting methods are controlled in accordance with MSFC-STD-154A, MSFC-STD-136 and SASD 2573751. These documents require approved mounting methods, stress relief and component security.

#### Test:

QUALIFICATION TESTS - The SPA is subjected to the following qualification testing:

VIBRATION: Each axis of the QM is subjected to Flight Acceptance Vibration Test (FAVT), Qualification Acceptance Vibration Test (QAVT), and Qualification Vibration Tests (QVT) in accordance with the SPA Vibration Test Procedure (826586). The level and duration for FAVT is as per Figure 6 and Table 2 of 826586; the level and duration for QAVT is as per Figure 7 and Table 2 of 826586; the level and duration for QVT is as per Figure 8 and Table of 826586. At the end of the three successive random vibration test in each axis, both directions (+/-) of each of the axis is subjected to a shock pulse test as per Figure 9 of 826586.

THERMAL/VACUUM: QM TVAC Test is in accordance with Figure 5 of the SPA TVAC Test Procedure (826588), with full Functional/Parametric Test performed at levels of +60 degrees C and -36 degrees C, and non-operating at -54 degrees C. The Qualification

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MECHANICAL ARM REASSEMBLY - The SPA's/Joints undergo a mechanical arm integration stage where electrical checks are performed per TP.2007.

MECHANICAL ARM-TESTING - The outgoing split-arm is configured on the Strongback and the Manipulator Arm Checkout is performed per ATP.1932.

FLIGHT CHECKOUT: PDRS OPS Checkout (all vehicles) JSC 16987.

### Inspection:

Units are manufactured under documented quality controls. These controls are exercised throughout design procurement, planning, receiving, processing, fabrication, assembly, testing and shipping of the units. Mandatory inspection points are employed at various stages of fabrication, assembly, and test. Government source inspection is invoked at various control levels.

EEE parts inspection is performed as required by SPAR-RMS-PA.003. Each EEE part is qualified at the part level to the requirements of the applicable specification. All EEE parts are 100% screened and burned-in, as a minimum, as required by SPAR-RMS-PA.003, by the supplier. DPA is performed as required by PA.003 on a randomly selected 5% of parts, maximum 5 pieces, minimum 3 pieces for each lot number/date code of parts received. All cavity devices are subjected to 100% PIND. Wire is procured to specification MIL-W-22759 or MIL-W-81381 and inspected and tested to NASA JSCM8080 Standard Number 9SA.

Receiving inspection verifies that all parts received are as identified in the procurement documents, that no physical damage has occurred to parts during shipment, that the receiving documents provide adequate traceability information and screening data clearly identifies acceptable parts.

Parts are inspected throughout manufacture and assembly as appropriate to the manufacturing stage completed. These inspections include: Printed circuit board inspection for track separation, damage and adequacy of plated through holes, component mounting inspection for correct soldering, wire looping, strapping, etc. Operators and inspectors are trained and certified to NASA NHB 5300.4(3A-1) Standard. Conformal coating inspection for adequate processing is performed using ultraviolet light techniques. P.C. Board installation inspection includes checks for correct board installation, alignment of boards, proper connector contact mating, wire routing, strapping of wires etc. Post P.C. Board installation inspection includes cleanliness and workmanship (Spar/government rep. mandatory inspection point).

Unit Pre-Acceptance Test inspection, which includes an audit of lower tier inspection completion, as built configuration verification to as design etc (mandatory inspection point). A unit Test Readiness Review (TRR) which includes verification of test personnel, test documents, test equipment calibration/validation status and hardware configuration is convened by QA in conjunction with Engineering, Reliability, Configuration Control, Supplier as applicable, and the government representative, prior to the start of any formal testing (Acceptance or Qualification). Unit level Acceptance Testing (ATP) includes ambient performance, thermal and vibration testing (Spar/government rep. mandatory inspection point).

Integration of unit to Joint SRU - Inspections include grounding checks, connectors for bent or pushback contacts, visual, cleanliness, interconnect wiring and power up test to the appropriate Joint Inspection Test Procedure (ITP). Joint level Pre-Acceptance Test Inspection, includes an audit of lower tier inspection completion, as built configuration verification to as design etc. Joint level Acceptance Testing (ATP) includes ambient and vibration testing (Spar/government rep. mandatory inspection point).

Mechanical Arm Reassembly - the integration of mechanical arm subassemblies to form the assembled arm. Inspections are performed at each phase of integration which includes electrical checks, through wiring checks, wiring routing, interface connectors for bent or pushback contacts etc Mechanical Arm Testing - Strongback and flat floor ambient performance test (Spar/government rep. mandatory inspection point).

OMRSD Offline: Power-up arm and drive each joint in Single Joint mode. Verify no Position Encoder BITE errors.

OMRSD Online None.  
Installation:

OMRSD Online Power-up arm. Verify no Position Encoder BITE errors.  
Turnaround:

Screen Failure: A: Pass  
B: Pass  
C: Pass

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Engineer	Hiltz, Michael / SPAR-BRAMPTON	Systems Engineer	4034	06Mar98	Signed
Reliability	Molgaard, Lena / SPAR-BRAMPTON	Reliability Engineer	4590	06Mar98	Signed
Program Management Office	Rice, Craig / SPAR-BRAMPTON	Technical Program Manager	4892	06Mar98	Signed
Subsystem Manager	Glenn, George / JSC-ER	RMS Subsystem Manager	(281) 483-1516	30Mar98	Signed
Technical Manager	Allison, Ron / JSC-MV6	RMS Project Engineer JSC	(713) 483-4072	09Apr98	Signed

*SAFETY + MISSION ASSURANCE COORD, DAND / JSC-NC RMS SYMA ENGINEER (281) 483-3077 29 APR 98 David G. Con*